

S37711EK5E

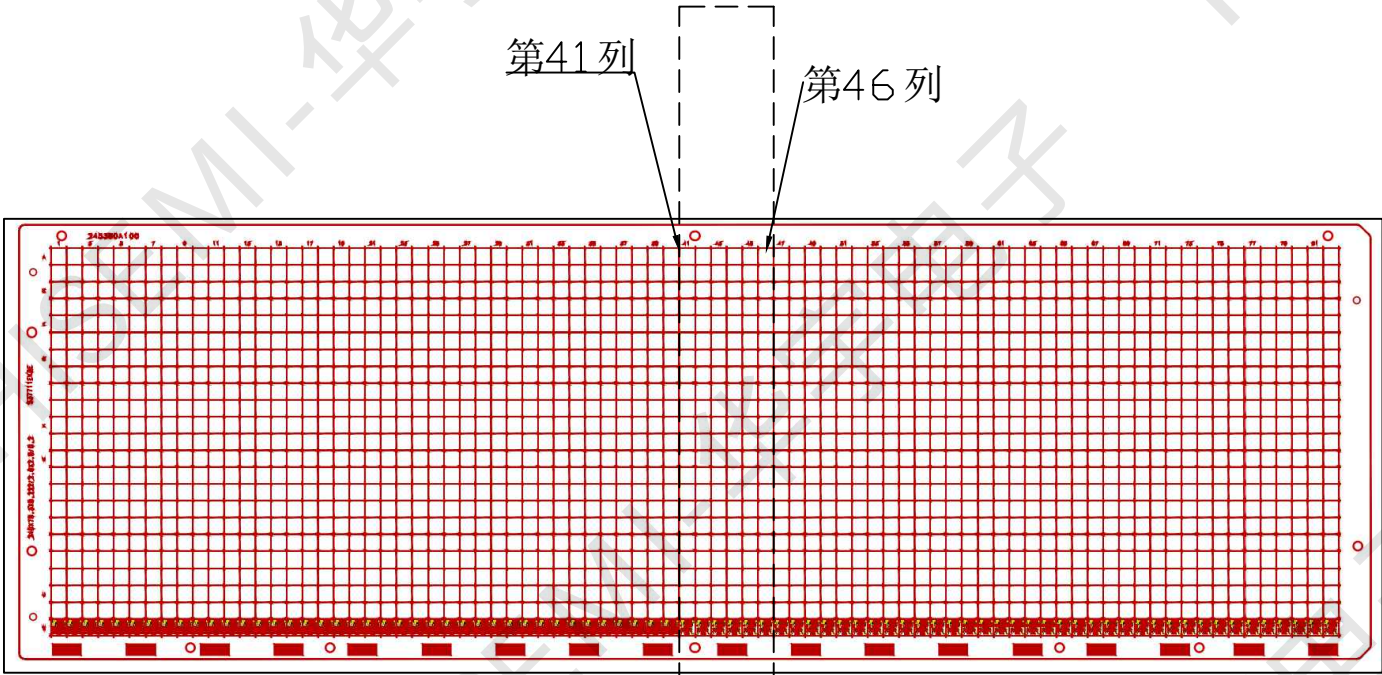
贴装区域：MPW基板

贴装V1区域：左起

左起41~46列

V1版本 6X23=138颗

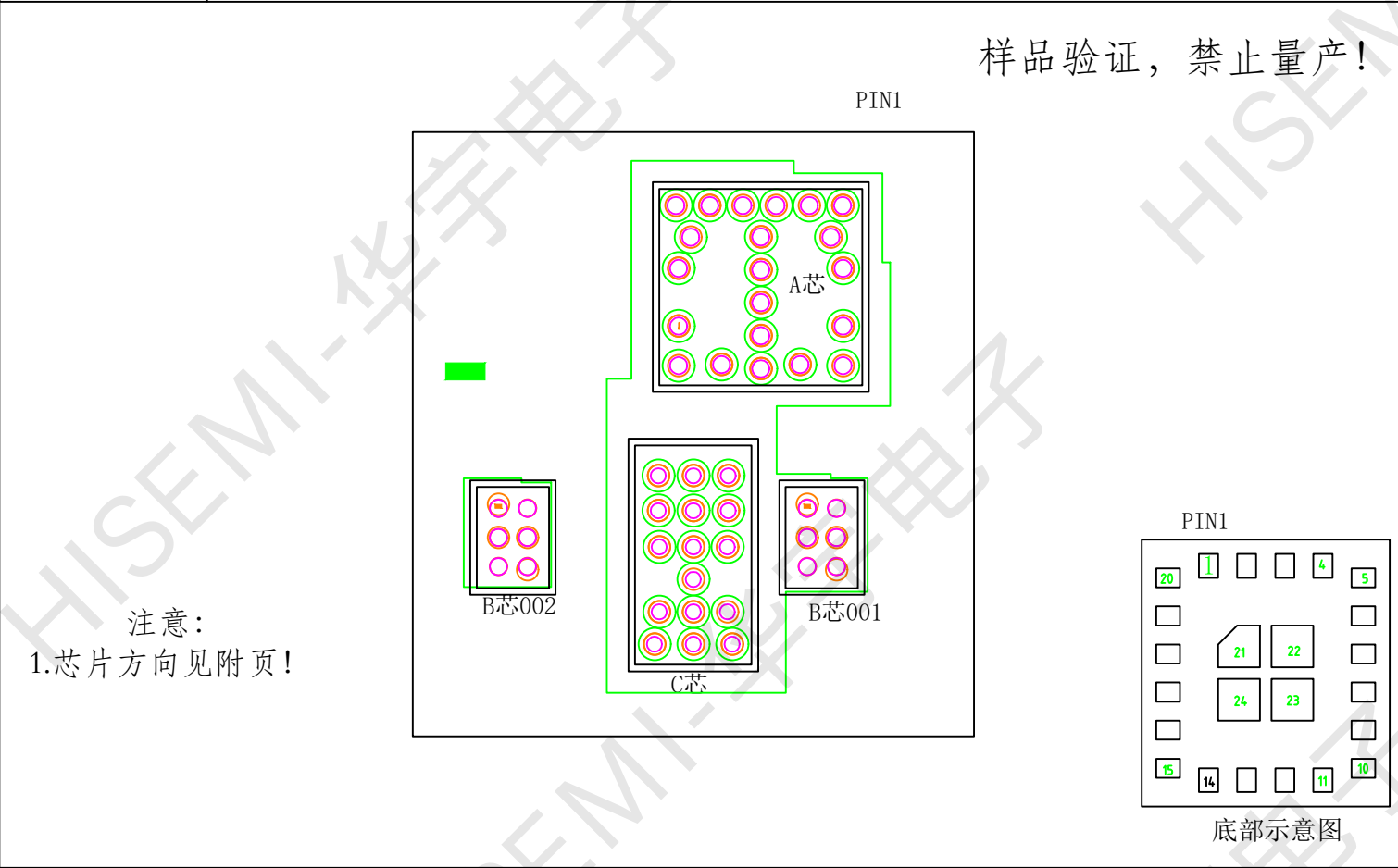
样品验证，禁止量产！

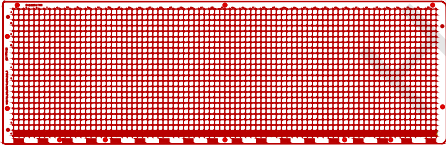


➞ 进料方向

 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.		1200		线图号 Drawing No.		HY-PX-1200-009 A		页码 Page 2 / 4		
	产品名称 Product Type		STR31277-21 E1.0		封装外型 PKG Type		FCLGA24L (2.8X2.6X0.722-P0.4)				
助焊剂 Flux	/	/	/	/	/	塑封料型号(绿色环保) Compound Type (Green)			基板编码 Substrate No.		
WF-6317	/	/	/	/	/	首选(Preferred): G311QL 备选(Optional):			S37711EK5E		
客户图号 Customer drawing NO.											

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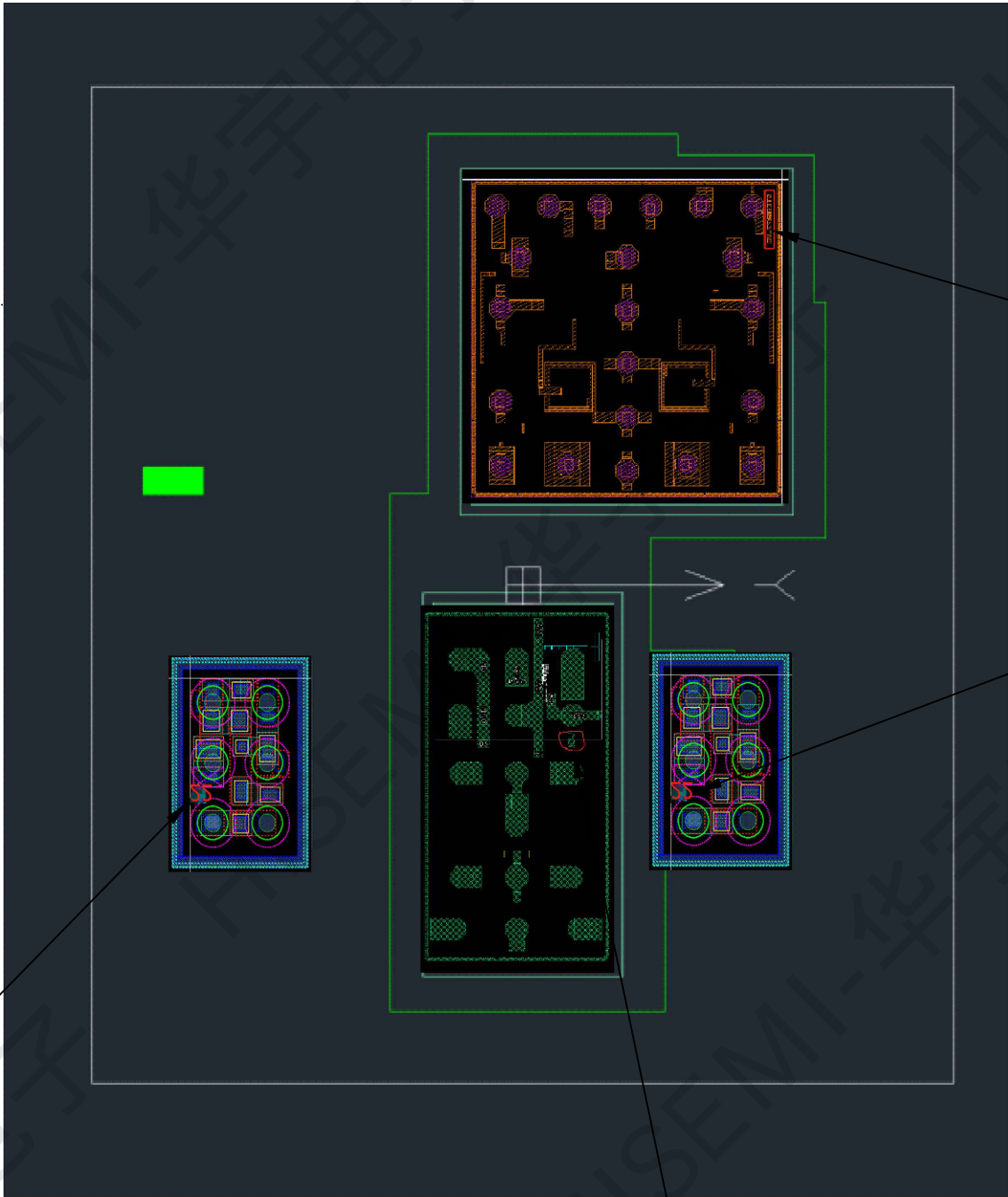


框架传送方向（装片）： L/F Direction (D/A)：上侧三个圆孔				实物图： Chip photo:				特殊说明 Special Instructions：			
								SMT注意： 1.装片位置公差为±25um；			

序号	芯片名称	Die ID	芯片尺寸 (with scribe line)	划片道 宽度	晶圆 尺寸	圆片 工艺	芯片厚度 UM	来料 方式	Wafer material*	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM
A 芯 U1	WUM577SD1M -V0	STR51277 _V0	971.9*1001.6(μm²) 38.26*39.44(mil²)	62um	8 寸	130nm	200um (不包含 bump高度)	卷带	SI	Pillar bump	68um (35Cu+3Ni+ 30SnAg)	152.19	68	80
B 芯 U2/U3	WSD577GD1E	22	395*530(μm²) 15.56*20.87(mil²)	60um	8 寸	3um	200um (不包含 bump高度)	晶圆 wafer	SI (RX Filter)	Pillar bump	93um (55Cu+3Ni+ 35SnAg))	135	93	80
C 芯 U4	WUM377SD1M -V01	V01	1079*602(μm²) 42.48*23.70(mil²)	62um	8 寸	130nm	200um (不包含 bump高度)	卷带	SI	Pillar bump	68um (35Cu+3Ni+ 30SnAg)	150	68	70
拟制 Prepared by				制图日期 Create Date			2025/4/21		生效日期 Effective Date				客户确认签字/盖章: Customer Signature	
研发审核 R&d check				产品工程审核 Product engineering check					批准 Approved by					

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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logo:
STR51277
_V0

logo:
22

LOGO:
22

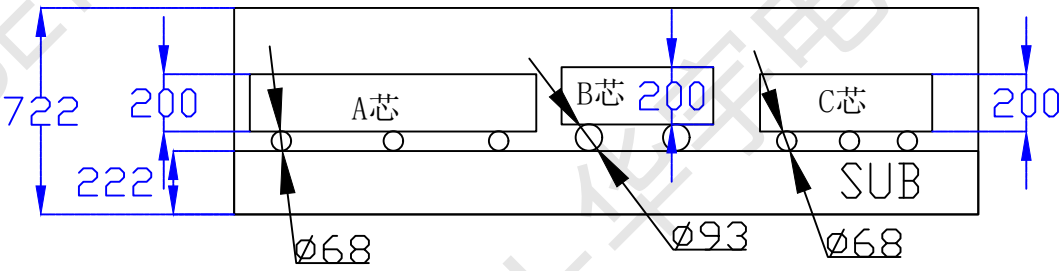
logo:
V01

拟制 Prepared by		制图日期 Create Date	2025/4/21	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
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